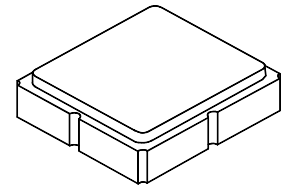


SF2425E

**868.6 MHz
SAW Filter**



SM3030-8

- **868.6 MHz Low-loss SAW Filter**
- **Surface Mount 3.0 x 3.0 mm Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	15	dBm
DC Voltage on any Non-ground Terminal	5	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

Electrical Characteristics

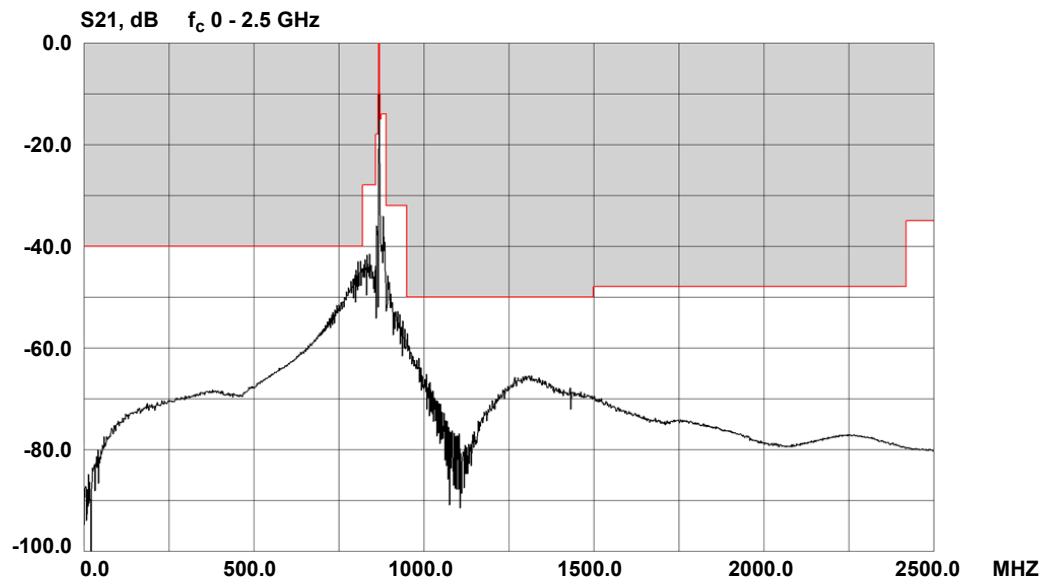
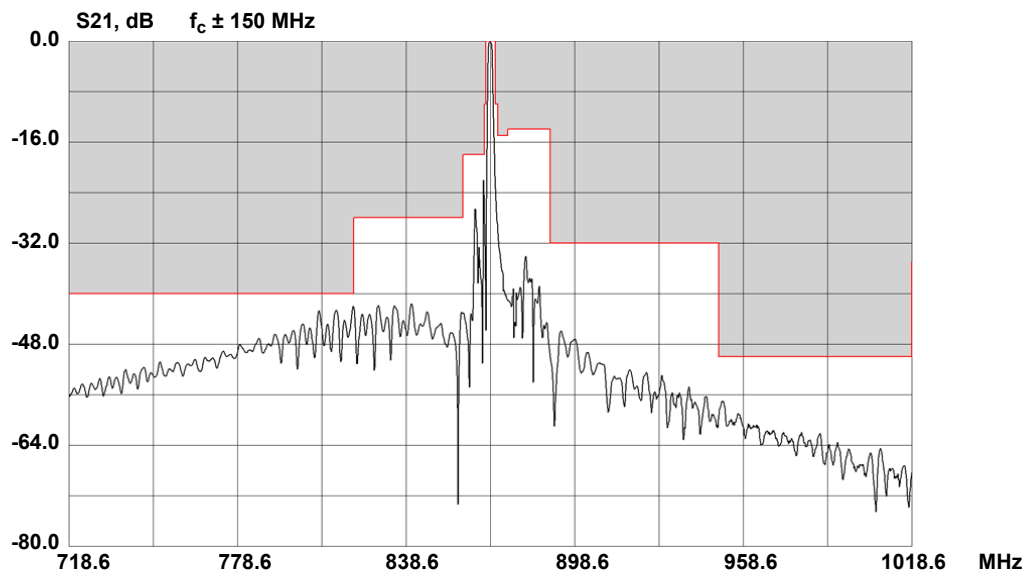
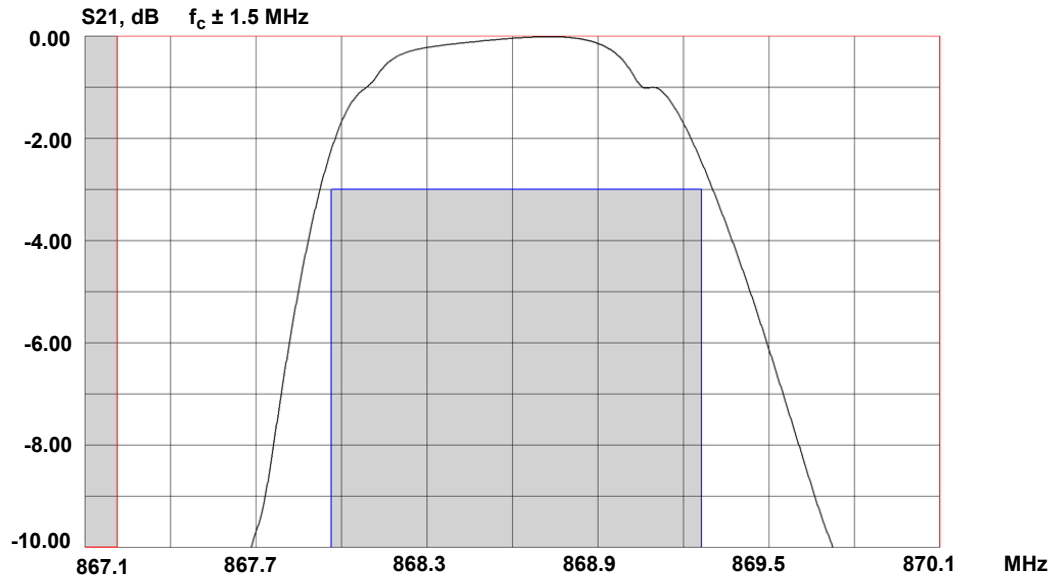
Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			868.6		MHz
Minimum Insertion Loss, incl. loss of matching elements	IL_{MIN}			2.65	3.50	dB
3dB BW			1.3	1.5		MHz
Attenuation (Relative to IL_{min})						dB
10.00 to 820.00 MHz			40	45		
820.00 to 859.00 MHz			28	33		
859.00 to 866.60 MHz			18	23		
866.60 to 867.20 MHz			10	14		
870.40 to 871.40 MHz			10	20		
871.40 to 875.00 MHz			15	19		
875.00 to 890.00 MHz			14	17		
890.00 to 950.00 MHz			32	36		
950.00 to 1500.00 MHz			50	55		
1500.00 to 2420.00 MHz			48	65		
2420.00 to 2500.00 MHz			-35	-40		
Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization, Y=year, WW=week, S=shift, dot=pin 1 indicator	8J, YWWS					
INPUT $Z_{in} = R_{in} C_{in}$				386 1.6		ΩpF
OUTPUT $Z_{out} = R_{out} C_{out}$				371 1.8		

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

NOTES:

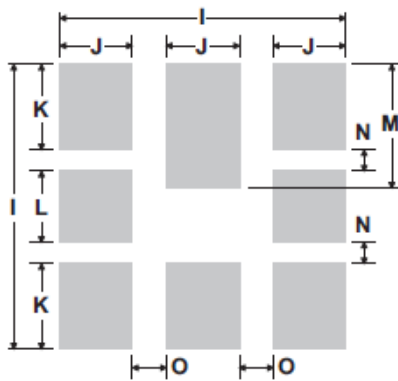
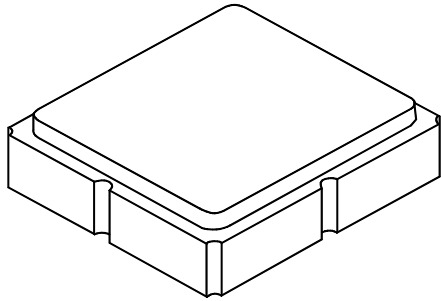
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Frequency Characteristics



SM3030-8 Case

8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint

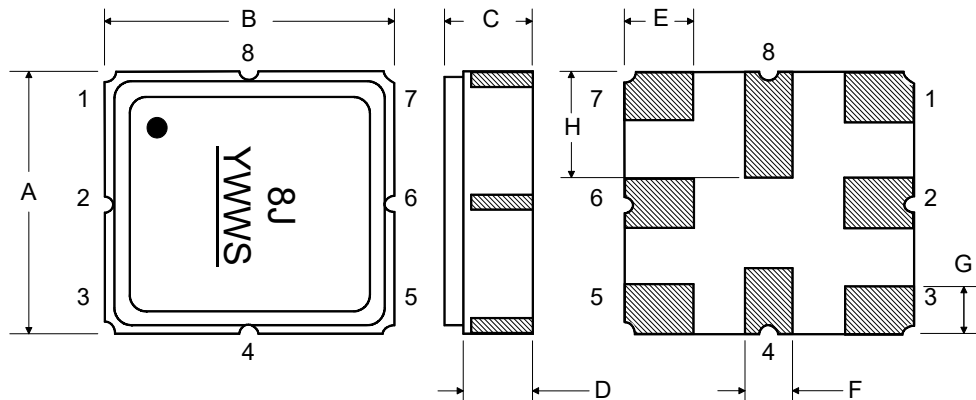


PCB Land Pattern
Top View

Electrical Connections

Connection	Terminals
Input Ground or Input	1
Input or Input Ground	2
Output Ground or Output	5
Output or Output Ground	6
Ground	3, 4, 7, 8

TOP VIEW



BOTTOM VIEW

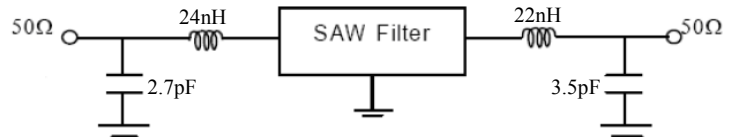
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	-	-	1.10	-	-	0.043
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

Test Circuit



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

